

**Notice of References Cited**

Application/Control No.

10/783,462

Applicant(s)/Patent Under  
Reexamination  
FILIPPI ET AL.

Examiner

Steven J. Fulk

Art Unit

2891

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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**NON-PATENT DOCUMENTS**

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	V	Huston et al., "Reliability Defect Detection and Screening During Processing - Theory and Implementation," IEEE/IRPS, January 1992, pp. 268-275.
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.